

/ Descriptions

Silicon NPN transistor in a TO-92 Plastic Package.

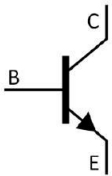
/ Features

Small reverse transfer capacitance, low noise figure.

/ Applications

High frequency amplifier, FM,RF,MIX IF amplifier applications.

/ Equivalent Circuit



/ Pinning



PIN1 Base PIN 2 Collector PIN 3 Emitter

/ hFE Classifications & Marking

h _{FE} Classifications Symbol	R	O	Y
h _{FE} Range	40~80	70~140	100~200

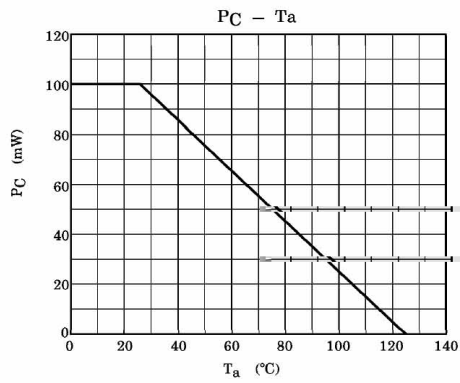
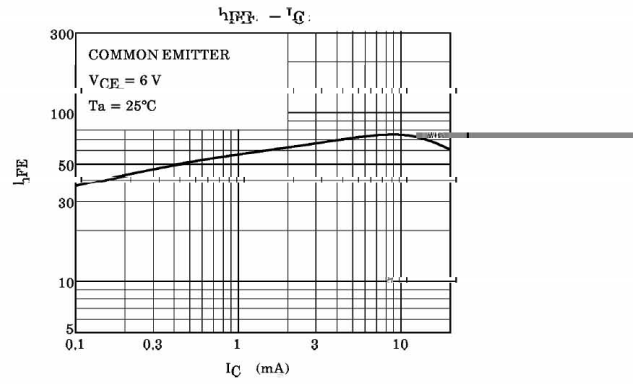
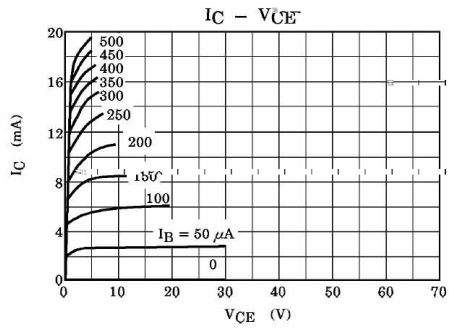
/ Absolute Maximum Ratings(Ta=25)

Parameter	Symbol	Rating	Unit
Collector to Base Voltage	V_{CBO}	40	V
Collector to Emitter Voltage	V_{CEO}	30	V
Emitter to Base Voltage	V_{EBO}	4.0	V
Collector Current - Continuous	I_C	20	mA
Emitter Current - Continuous	I_E	-20	mA
Collector Power Dissipation	P_C	100	mW
Junction Temperature	T_j	150	
Storage Temperature Range	T_{stg}	-55 150	

/ Electrical Characteristics(Ta=25)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Collector Cut-Off Current	I_{CBO}	$V_{CB}=40V$ $I_E=0$			0.5	A
Emitter Cut-Off Current	I_{EBO}	$V_{EB}=4.0V$ $I_C=0$			0.5	A
DC Current Gain	h_{FE}	$V_{CE}=6.0V$ $I_C=1.0mA$	40		200	
Transition Frequency	f_T	$V_{CE}=6.0V$ $I_C=1.0mA$		550		MHz
Power Capacitance Gain	G_{pe}	$V_{CC}=6.0V$ $f=100MHz$ $I_E=-1.0mA$		18		dB
Noise Figure	NF	$V_{CC}=6.0V$ $f=100MHz$ $I_E=-1.0mA$		2.5	5.0	dB
Collector- Base Time Constant	$C_{C.rbb'}$	$V_{CE}=6.0V$ $f=30MHz$ $I_E=-1.0mA$			20	pS
Reverse Transfer Capacitance	C_{re}	$V_{CE}=6.0V$ $f=1.0MHz$		0.70		pF

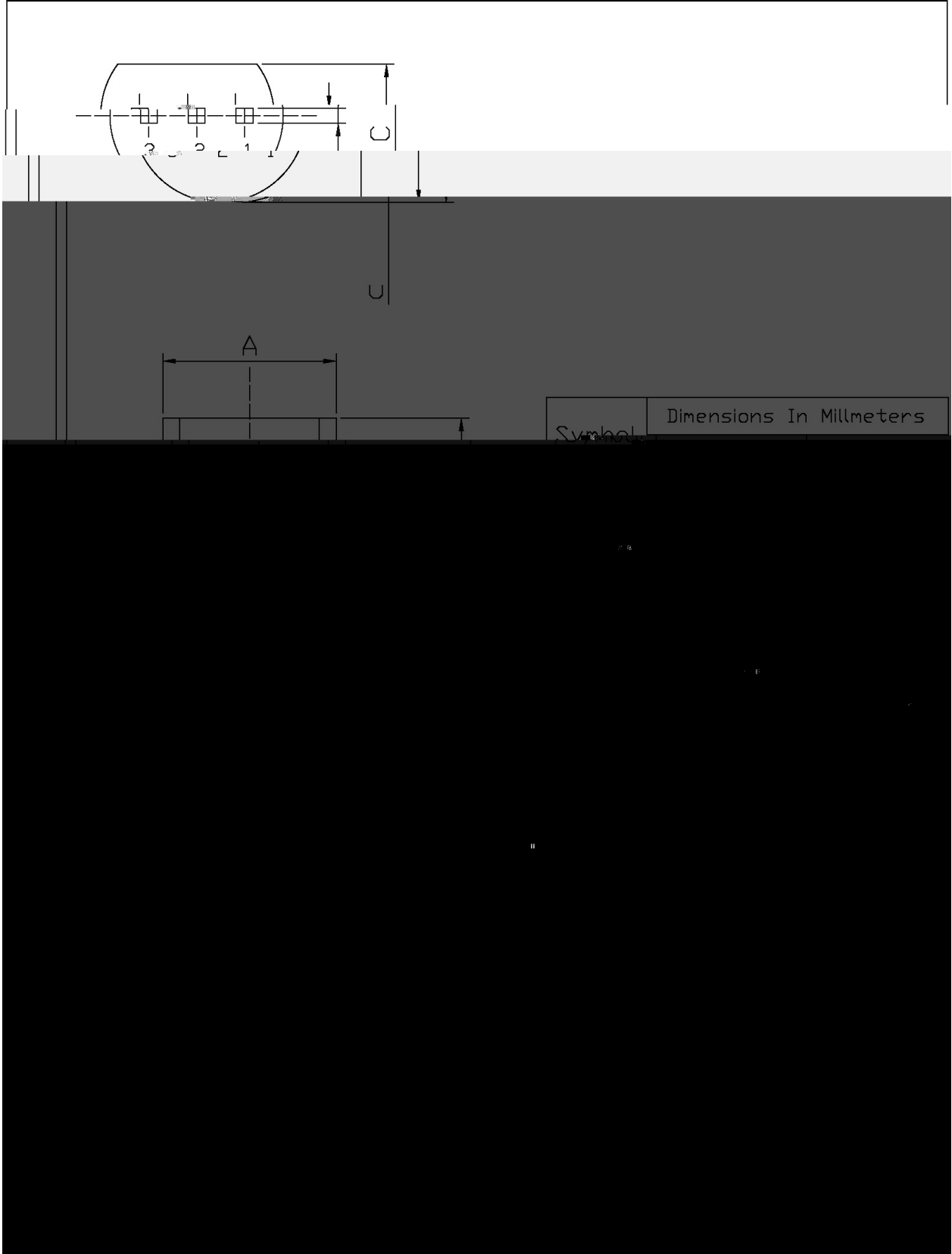
/ **Electrical Characteristic Curve**



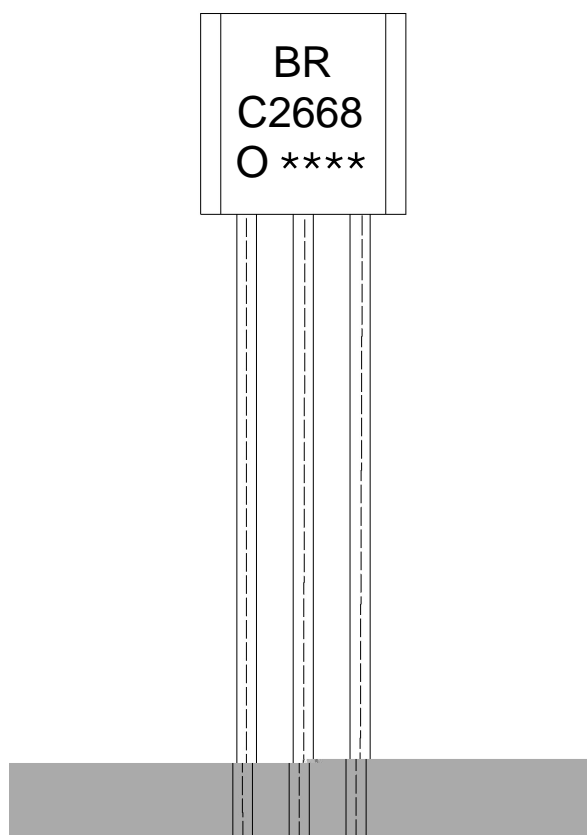
/ Package Dimensions

TO-92

Unit: mm



/ Marking Instructions



Note:

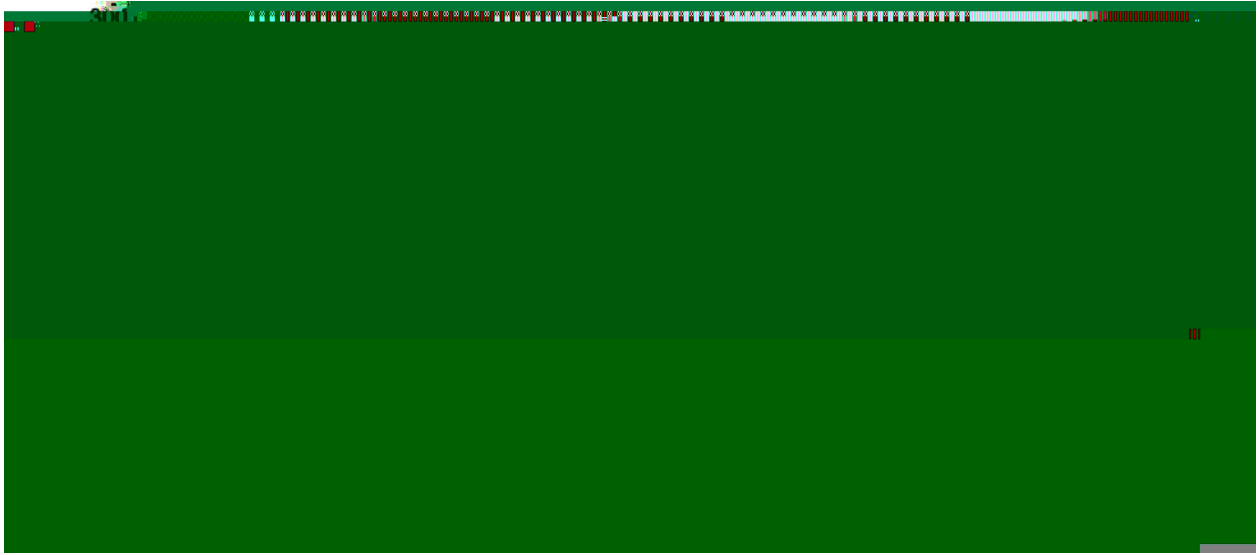
BR: Company Code.

C2668: Product Type.

O: h_{FE} Classifications Symbol

****: Lot No. Code, code change with Lot No.

() / Temperature Profile for Dip Soldering(Pb-Free)



Note:

- | | | | | | |
|---|-----|-----|----|----------|---|
| 1 | 25 | 150 | 60 | 90sec; | 1.Preheating:25~150 , Time:60~90sec. |
| 2 | 255 | 5 | 5 | 0.5sec; | 2.Peak Temp.:255 5 , Duration:5 0.5sec. |
| 3 | | | 2 | 10 /sec. | 3. Cooling Speed: 2~10 /sec. |

/ Resistance to Soldering Heat Test Conditions

270 5 10 1 sec. Temp:270±5 Time:10±1 sec

/ Packaging SPEC.

/ BULK

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm3)		
	Units/Bag 只/袋	Bags/Inner Box 袋/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Bag 袋	Inner Box 盒	Outer Box 箱
TO-92	1,000	10	10,000	5	50,000	135×190	237×172×102	560×245×195
	1,000	10	10,000	10	100,000	135×190	237×172×102	560×245×375

/ AMMO

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm3)	
	Units/tape 只/纸带	Tape/Inner Box 纸带/盒	Rows/Inner Box 纸带层/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Inner Box 盒	Outer Box 箱
TO-92	3,000	1	120	10	30,000	328×230×42	小箱 480×346×235, 大箱 547×407×268

/ Notices